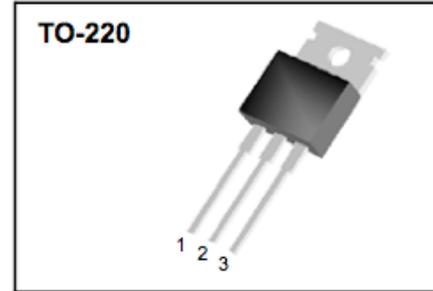
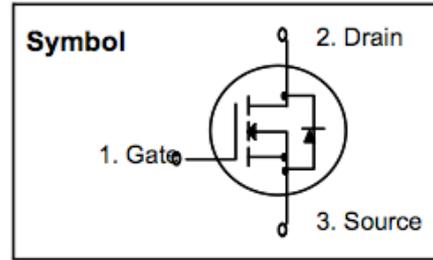


## MS85N06 60V N-Channel MOSFET

### FEATURES

- RDS(on) (Max 0.013  $\Omega$  )@VGS=10V
- Gate Charge (Typical 70nC)
- Improved dv/dt Capability, High Ruggedness
- 100% Avalanche Tested
- Maximum Junction Temperature Range (175°C)



### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

#### Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise specified)

Symbol	Parameter	Value	Unit
V <sub>DSS</sub>	Drain-Source Voltage	60	V
I <sub>D</sub>	Drain Current -Continuous (T <sub>c</sub> =25°C)	85	A
	Drain Current -Continuous (T <sub>c</sub> =100°C)	60	A
I <sub>DM</sub>	Drain Current -Pulsed	340	A
V <sub>GS</sub>	Gate-Source Voltage	±20	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	929	mJ
E <sub>AR</sub>	Repetitive Avalanche Energy	17.6	mJ
d <sub>v</sub> /d <sub>t</sub>	Peak Diode Recovery dv/dt	7.0	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>c</sub> =25°C)	176	W
	- Derate above 25°C	1.17	W/°C
T <sub>J</sub> ,T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to + 175	°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C

• Drain current limited by maximum junction temperature

### Thermal Resistance Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	--	0.85	°C/W
$R_{\theta JA}$	Junction-to-Ambient	--	62.5	

### Electrical Characteristics (T<sub>c</sub>=25°C unless otherwise specified)

Symbol	Parameter	Test Conditions	Min	Type	Max	Units
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### Off Characteristics

$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{ V}, I_D=250\mu\text{A}$	60	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D=250\mu\text{A}$ , Referenced to 25°C	--	0.07	--	V/°C
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=60\text{ V}, V_{GS}=0\text{ V}$	--	--	10	μA
		$V_{DS}=48\text{ V}, V_C=125^\circ\text{C}$	--	--	100	μA
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS}=-20\text{ V}, V_{DS}=0\text{ V}$	--	--	-100	nA

### On Characteristics

$V_{GS}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2.0	--	4.0	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{ V}, I_D=42.5\text{ A}$	--	10.5	13	mΩ

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS}=25\text{ V}, V_{GS}=0\text{ V},$ $f=1.0\text{ MHz}$	--	2500	--	pF
$C_{oss}$	Output Capacitance		--	900	--	pF
$C_{rss}$	Reverse Transfer Capacitance		--	160	--	pF

### Switching Characteristics

$t_{d(on)}$	Turn-On Time	$V_{DS}=42.5\text{ V}, I_D=30\text{ A},$ $R_G=25\Omega$	--	40	--	ns
$t_r$	Turn-On Rise Time		--	200	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	150	--	ns
$t_f$	Turn-Off Fall Time		--	150	--	ns
$Q_g$	Total Gate Charge	$V_{DS}=48\text{ V}, I_D=85\text{ A},$ $V_{GS}=10\text{ V}$	--	70	--	nC
$Q_{gs}$	Gate-Source Charge		--	20	--	nC
$Q_{gd}$	Gate-Drain Charge		--	30	--	nC

**Source-Drain Diode Maximum Ratings and Characteristics**

$I_S$	Continuous Source-Drain Diode Forward Current		--	--	85	A
$I_{SM}$	Pulsed Source-Drain Diode Forward Current		--	--	340	
$V_{SD}$	Source-Drain Diode Forward Voltage	$I_S=85A, V_{GS}=0V$	--	--	1.5	V
$t_{rr}$	Reverse Recovery Time	$I_S=85 A, V_{GS}= 0V$	--	70	--	ns
$Q_{rr}$	Reverse Recovery Charge	$di_F/dt=100A/\mu s$	--	130	--	$\mu C$

**Notes;**

1. Repeativity rating : pulse width limited by junction temperature
2.  $L = 150\mu H$ ,  $I_{AS} = 85A$ ,  $V_{DD} = 25V$ ,  $R_G = 25\Omega$  , Starting  $T_J = 25^\circ C$
3.  $I_{SD} \leq 85A$ ,  $di/dt \leq 300A/\mu s$ ,  $V_{DD} \leq BVDSS$ , Starting  $T_J = 25^\circ C$
4. Pulse Test : Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$
5. Essentially independent of operating temperature.